

NOTES: UNLESS OTHERWISE SPECIFIED

1. FOR GENERAL SERIES SPECIFICATIONS, SEE SDXX-0000.

2. MATERIAL AND FINISHES:

BODY: BRASS, NICKEL PLATE  
HOUSING: BRASS, GOLD PLATE  
CONTACT: BERYLLIUM COPPER, GOLD PLATE  
INSULATOR: PTFE, NATURAL

3. ELECTRICAL SPECIFICATIONS:

IMPEDANCE: 75 OHMS  
FREQUENCY RANGE: DC-12 GHz  
RETURN LOSS: < -15 dB UP TO 6.0 GHz  
DIELECTRIC WITHSTANDING VOLTAGE: 1000VRMS MIN.  
INSULATION RESISTANCE: 10,000 MEGOHMS MIN.

4. MECHANICAL:

DURABILITY: 500 CYCLES MIN

5. ENVIRONMENTAL:

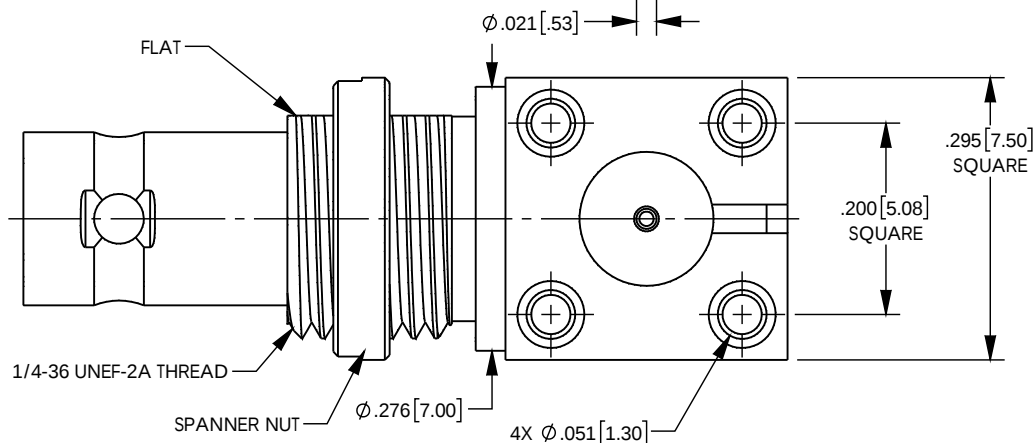
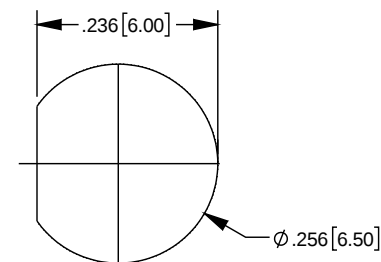
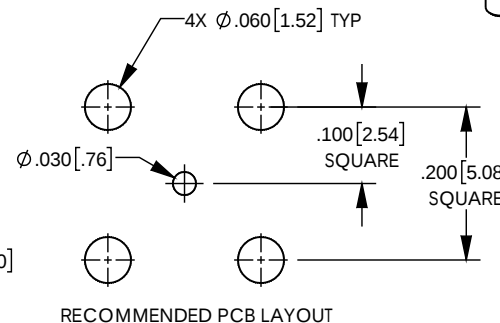
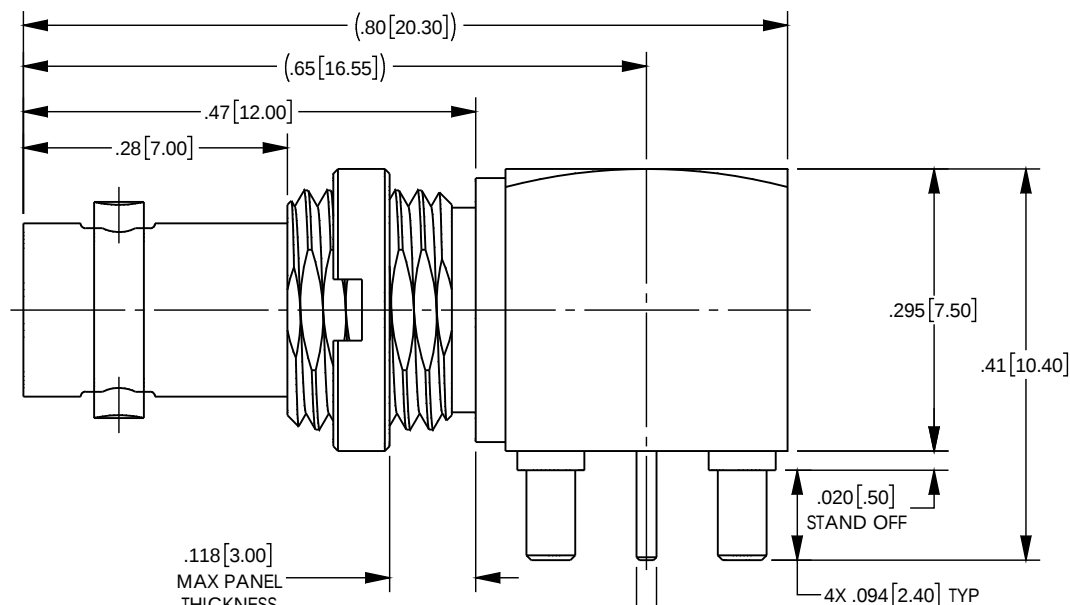
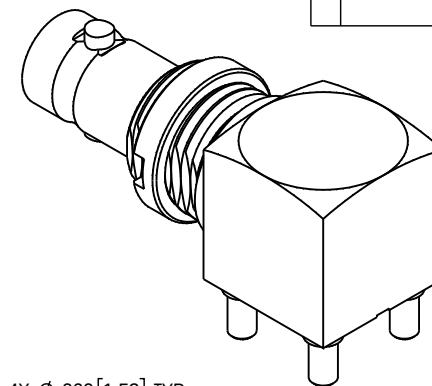
THERMAL SHOCK PER MIL-STD-202 METHOD 107  
TEST CONDITIONS B (EXCEPT HIGH TEMP @200° C)  
VIBRATION: MIL-STD-202 METHOD 204 TEST CONDITION B  
SHOCK: MIL-STD-202 METHOD 213 TEST CONDITION B  
CORROSION: MIL-STD-202 METHOD 101  
TEST CONDITIONSB 5% SALT SOLUTION

6. PACKAGING:

INDIVIDUALLY BAGGED

7. COMPLIANT TO 3G/6G/12G-SDI SMPTE REQUIREMENTS.

| REV | DESCRIPTION | BY DATE  | APPD |
|-----|-------------|----------|------|
| B   | ER063190    | 06/06/16 | Y/A  |



CATALOG P/N: HHD364HDE704

PER ASME Y14.5M-1994  
UNLESS OTHERWISE SPECIFIED:  
DIMENSIONS ARE IN INCHES [MM]  
TOLERANCES:  
DECIMAL: .XX [X.X] ± .01 [0.3]  
.XXX [X.XX] ± .005 [0.13]  
.XXXX [X.XXX] ± .000X  
ANGLES: ± 2° SCALE: 5:1

**KINGS**  
by WINCHESTER  
Winchester Electronics Corporation  
199 Park Road Ext Suite 104  
Middlebury, Connecticut 06762

| CUSTOMER SALES DRAWING |          |          |          | THIRD ANGLE |
|------------------------|----------|----------|----------|-------------|
| DRAWN                  | DATE     | APPROVED | DATE     |             |
| KPL                    | 11/22/13 | MS       | 11/22/13 |             |
| APPROVED               | DATE     | APPROVED | DATE     |             |
| XXX                    | XX/XX/XX | XXX      | XX/XX/XX |             |

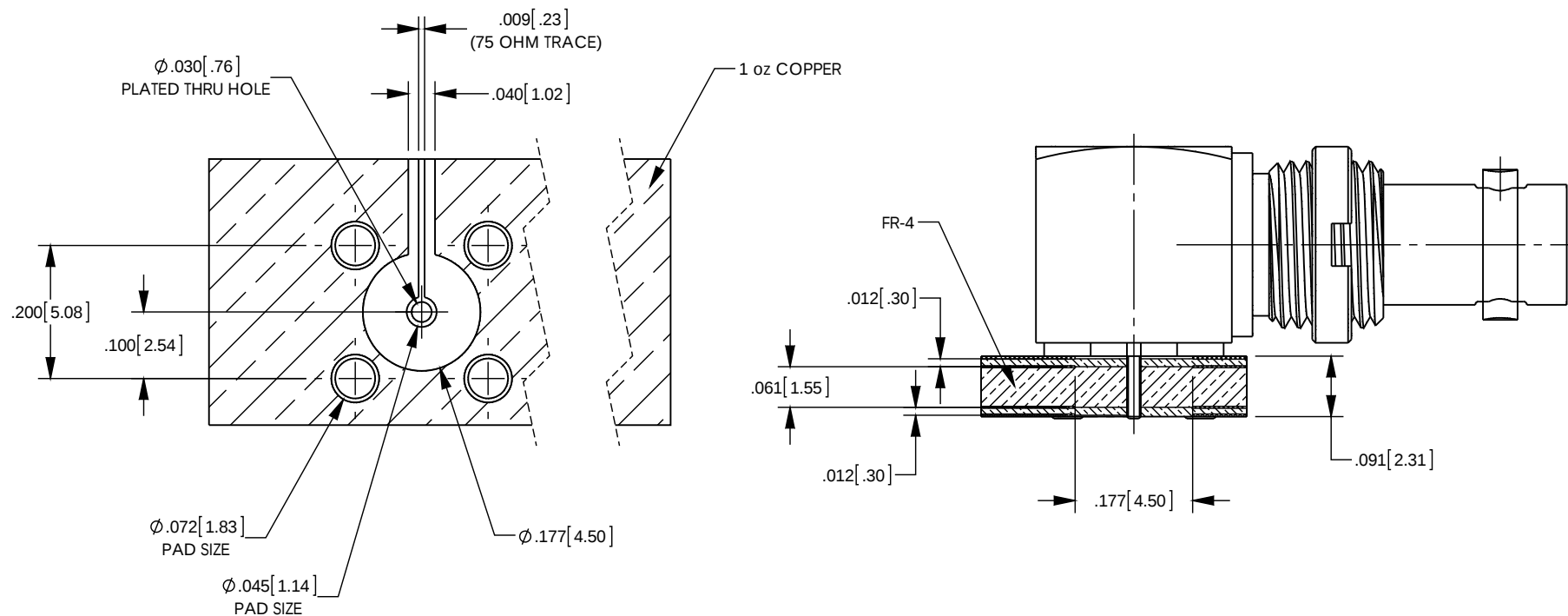
|                              |                |        |     |
|------------------------------|----------------|--------|-----|
| HD-BNC RA BHD JACK PCB MOUNT |                |        |     |
| <b>A</b>                     | SDHHD364HDE704 | SHT OF | REV |
|                              |                | 1 2    | B   |

CONFIGURATION - 0  
( 4-LAYER STACKUP)

## PROPOSED PCB MOUNTING AND LAUNCH FOR OPTIMAL RF PERFORMANCE

VARIATIONS IN BOARD DIELECTRIC MATERIAL AND TRACE ROUTING MAY REQUIRE DIFFERENT GEOMETRY  
(STANDARD FR-4 EPOXY IS ASSUMED HERE,  $\epsilon_r=4.40$ )

### BOTTOM LAYER ( SIGNAL )



| REV | DESCRIPTION                                   | BY  | DATE       | APPROVED |
|-----|-----------------------------------------------|-----|------------|----------|
| 01  | PRELIMINARY DRAWING ER050504                  | KPL | 11/22/2013 | MS       |
| 02  | UPDATED TO 8 P/N TO HDH364HDE704 PER ER051495 | CY  | 01/22/14   | YA       |

|                                                                                                                                                                                    |            |             |            |
|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------|-------------|------------|
| PER ASME Y14.5M-1994<br>UNLESS OTHERWISE SPECIFIED:<br>DIMENSIONS ARE IN INCHES<br>TOLERANCES:<br>DECIMAL: .XX ± .XX<br>.XXX ± .XXX<br>.XXXX ± .XXXX<br>ANGLES: ± X°<br>SCALE: 3:1 |            | THIRD ANGLE |            |
| MATERIAL                                                                                                                                                                           |            | FINISH      |            |
| DRAWN                                                                                                                                                                              | DATE       | APPROVED    | DATE       |
| KPL                                                                                                                                                                                | 11/22/2013 | MS          | 06/17/2016 |
| APPROVED                                                                                                                                                                           | DATE       | APPROVED    | DATE       |
| XXX                                                                                                                                                                                | XX/XX/XX   | XXX         | XX/XX/XX   |

|                                                                                                                           |                |                                                                                                    |    |     |
|---------------------------------------------------------------------------------------------------------------------------|----------------|----------------------------------------------------------------------------------------------------|----|-----|
| <br><b>WINCHESTER</b><br>ELECTRONICS |                | Winchester Electronics Corporation<br>199 Park Road Ext Suite 104<br>Middlebury, Connecticut 06762 |    |     |
| HD BNC RA BHD JACK PCB MOUNT                                                                                              |                |                                                                                                    |    |     |
| <b>A</b>                                                                                                                  | SDHHD364HDE704 | SHT                                                                                                | OF | REV |
|                                                                                                                           |                | 2                                                                                                  | 2  | 02  |